GlobalFoundries™

Delivering pervasive semiconductors for humankind

Disclaimer

This presentation and the accompanying oral presentation include “forward-looking statements,” that reflect our current expectations and views of future events. These forward-looking statements are made under the “safe harbor” provisions of the U.S. Private Securities Litigation Reform Act of 1995 and include but are not limited to, statements regarding our financial outlook, future guidance, product development, business strategy and plans, and market trends, opportunities and positioning. These statements are based on current expectations, assumptions, estimates, forecasts, projections and limited information available at the time they are made. Words such as “expect,” “anticipate,” “should,” “believe,” “hope,” “target,” “project,” “goals,” “estimate,” “potential,” “predict,” “may,” “will,” “might,” “could,” “intend,” “shall,” “outlook,” “on track,” and variations of these terms or the negative of these terms and similar expressions are intended to identify these forward-looking statements, although not all forward-looking statements contain these identifying words. Forward-looking statements are subject to a broad variety of risks and uncertainties both known and unknown. Any inaccuracy in our assumptions and estimates could affect the realization of the expectations or forecasts in these forward-looking statements. For example, our business could be impacted by the COVID-19 pandemic and supply chain disruptions due to the Russia/Ukraine conflict and actions taken in response to such events; the market for our products may develop more slowly than expected or than it has in the past; our operating results may fluctuate more than expected; there may be significant fluctuations in our results of operations and cash flows related to our revenue recognition or otherwise; a network or data security incident that allows unauthorized access to our network or data or our customers’ data could damage our reputation; we could experience interruptions or performance problems associated with our technology, including a service outage; and global economic conditions could deteriorate. It is not possible for us to predict all risks, nor can we assess the impact of all factors on our business or the extent to which any factor, or combination of factors, may cause actual results or outcomes to differ materially from those contained in any forward-looking statements we may make. Moreover, we operate in a competitive and rapidly changing market, and new risks may emerge from time to time. You should not rely upon forward-looking statements as predictions of future events. These statements are based on our historical performance and on our current plans, estimates and projections in light of information currently available to us, and therefore you should not place undue reliance on them.

Although we believe that the expectations reflected in our statements are reasonable, we cannot guarantee that the future results, levels of activity, performance or events and circumstances described in the forward-looking statements will be achieved or occur. Moreover, neither we, nor any other person, assumes responsibility for the accuracy and completeness of these statements. Recipients are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date such statements are made and should not be construed as statements of fact. Except to the extent required by federal securities laws, we undertake no obligation to update any information or any forward-looking statements as a result of new information, subsequent events, or any other circumstances after the date hereof, or to reflect the occurrence of unanticipated events.

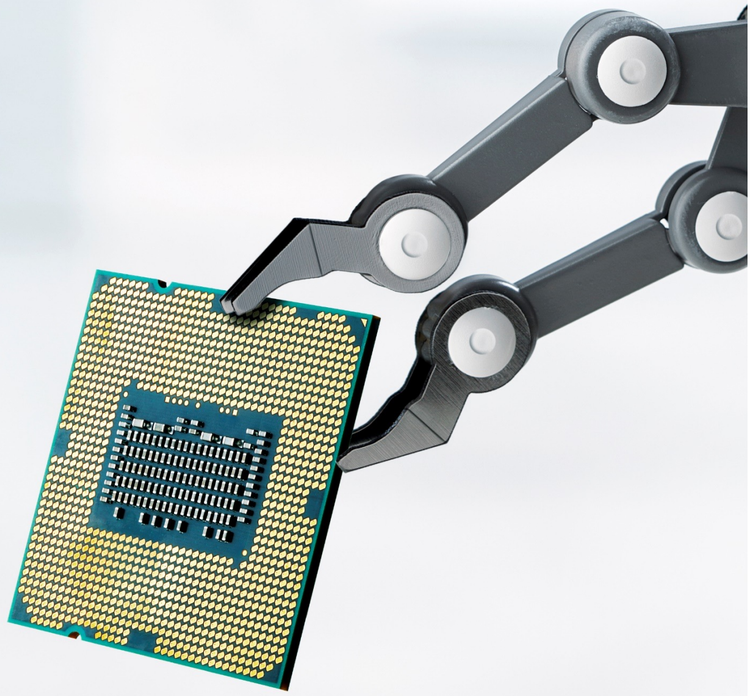
This presentation and the accompanying oral presentation also contain estimates and other statistical data made by independent parties and by us relating to market size and growth and other data about our industry and business. This data involves a number of assumptions and limitations, and you are cautioned not to give undue weight to such estimates. We have not independently verified the industry data generated by independent parties and contained in this presentation and, accordingly, we cannot guarantee their accuracy or completeness. In addition, projections, assumptions, and estimates of our future performance and the future performance of the markets in which we compete are necessarily subject to a high degree of uncertainty and risk.

In addition to the financial information presented in accordance with International Financial Reporting Standards (“IFRS"), this presentation includes the following adjusted non-IFRS metrics: adjusted gross profit (loss), adjusted gross margin, adjusted net income (loss), adjusted diluted earnings (loss) per share and adjusted EBITDA. We define adjusted gross profit (loss) as gross profit (loss) adjusted for share-based compensation expense. We define adjusted gross margin as adjusted gross profit (loss), which is gross profit (loss) before share-based compensation, divided by net revenues. We define adjusted operating profit (loss) as profit (loss) from operations adjusted for share-based compensation expense. We define adjusted operating margin as adjusted operating profit (loss) divided by net revenues. We define adjusted net income (loss) as net income (loss) adjusted for share-based compensation expense. We define adjusted diluted earnings (loss) per share as adjusted net income (loss) divided by the dilutive shares. We define adjusted EBITDA as net income (loss), excluding the impact of finance expense, income tax expense, depreciation, amortization, share-based compensation expense, transaction gains and associated expenses, restructuring charges and litigation settlements. We define adjusted EBITDA margin as adjusted EBITDA divided by net revenues.

We believe that in addition to our results determined in accordance with IFRS, these adjusted non-IFRS measures provide useful information to both management and investors in measuring our financial performance and highlight trends in our business that may not otherwise be apparent when relying solely on IFRS measures. These adjusted non-IFRS financial measures provide supplemental information regarding our operating performance that excludes certain gains, losses and non-cash charges that occur relatively infrequently and/or that we consider to be unrelated to our core operations. For further information regarding these non-IFRS measures, please refer to “Appendix” in this presentation.

Adjusted non-IFRS financial information is presented for supplemental informational purposes only and should not be considered in isolation or as a substitute for financial information presented in accordance with IFRS. Our presentation of adjusted non-IFRS measures should not be construed as an inference that our future results will be unaffected by unusual or nonrecurring items. Other companies in our industry may calculate these measures differently, which may limit their usefulness as a comparative measure.

GlobalFoundries™



GF at a glance

$6.6B
2021 revenue

2.4M
2021 wafer shipments
(300mm eq.)

>200
customers in 2021

5
manufacturing sites
across three continents

~15,000
employees

~10,000
patents

10.28.21
GFS Nasdaq listed

GF journey

Creation

GlobalFoundries was created based on the thesis that the world needed a geographically diverse alternative to Taiwan

Transformation

Strategically re-positioned to serve pervasive semiconductor end markets

- Strengthened management team aligned to mission
- Refocused investments & accelerated differentiated solutions focused on pervasive markets
- Increased single-sourced products
- Driving margin expansion and earnings growth

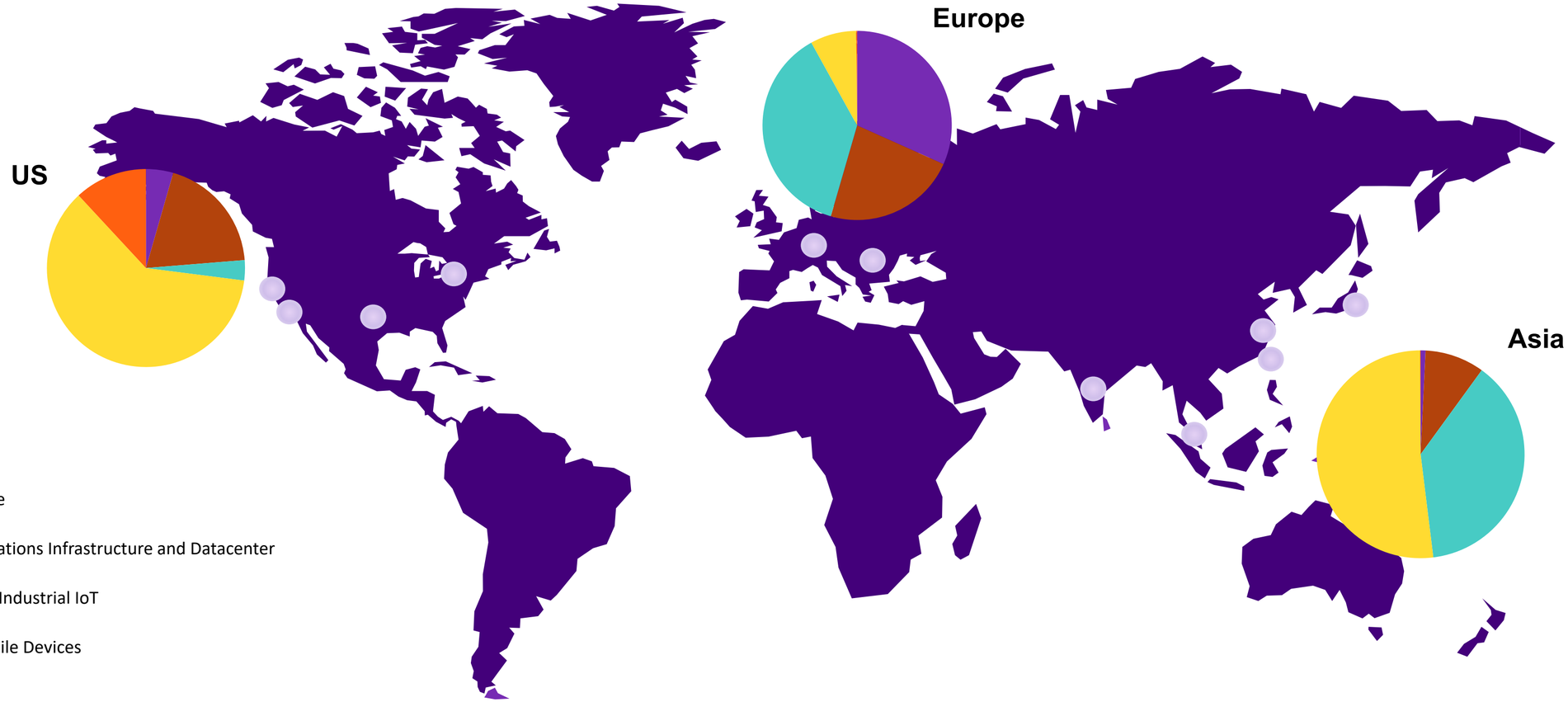
Realization

The world's leading manufacturer of feature-rich semiconductor solutions

- Gain share in secular end-markets
- Innovate in purpose-built platforms and solutions
- Capital efficient expansion through partnerships
- Deliver best-in-class financials

2009 — 2017 — 2018 — 2021 — 2022 2030

Delivering solutions to customers around the globe



10
Countries
and time zones

11
Service
languages

<10 km
Median proximity
to top customers

Purpose-built customer engagements

Certainty

~80%
2022-2025 capacity covered by LTAs

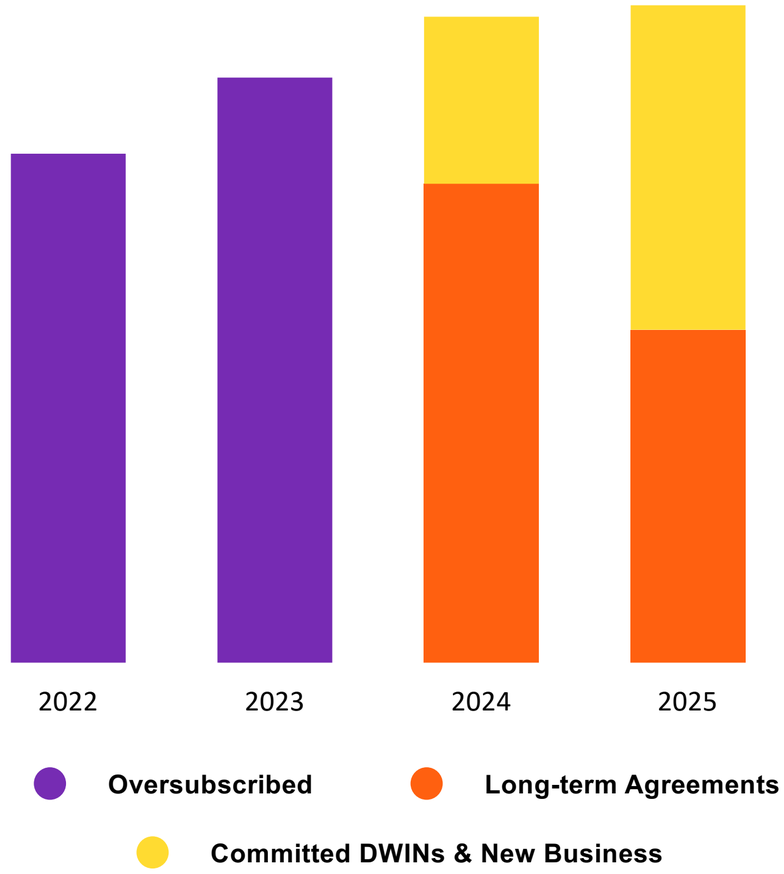
Durability

90%
single-sourced DWINs[1] in 1H'22

Profitability

↑19%
YoY mix and pricing increase 1H'21 - 1H'22[2]

Multi-year Capacity Coverage



Note:
1. A DWIN, or design win, is defined as the successful completion of the evaluation stage, where a customer has assessed our technology solution, verified that it meets its requirements, qualified it for their products and confirmed to us their selection.
2. Wafer hardware only

GF's ecosystem: more than a decade in the making

Design enablement network

IP	FDX™	RF	EDA	Design services	OSAT

Our partner community

100+
Ecosystem partners spanning IP, EDA, OSAT and design services

4500+
Total IP titles across all nodes from >50 IP partners

950+
IP titles currently in active development across 26 process nodes and 34 IP partners

300+
Clients enabled by ecosystem partner IPs in the last 5 years

1700+
Client designs enabled by ecosystem partners in the last 5 years

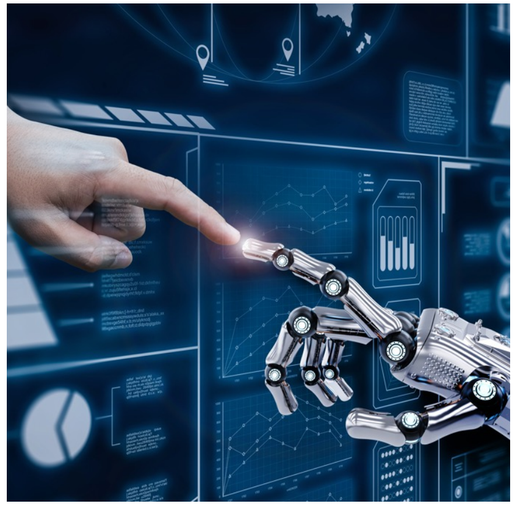
End-markets and Solutions

Technology megatrends shaping the global economy

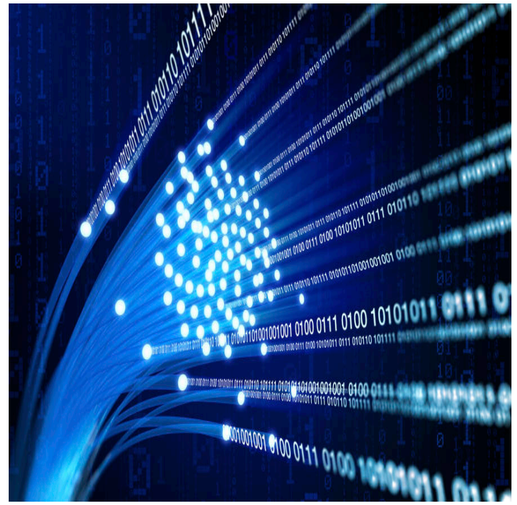
Smart, connected devices

Adoption of AR & VR

Explosion of AI & ML



Data everywhere



Megatrends accelerated or limited by semiconductors

Foundries are essential to global GDP

Market Size (2021)

$89T
Global GDP

$2.2T
Electronics

1,000s of companies

$595B
Semiconductors
~6% CAGR growth (21-26)

100s of companies

$96B
Foundry
~6% CAGR growth (21-26)

Only 5 at scale[1], 3 of which are in China and Taiwan

Semiconductors outpace GDP & foundry outpaces semiconductors

Source: Global GDP: World Bank, IMF. Electronics; Semiconductors and Foundry: Gartner "Forecast, Semiconductor Foundry Revenue, Supply and Demand, Worldwide, 1Q22 Update (April 2022)

Note:
1. Excludes smaller foundry players, defined as those with less than $2Bn of foundry revenue

Uniquely positioned in markets that matter

Smart Mobile Devices

Home and Industrial IoT

Automotive

Communications Infrastructure & Datacenter

Smart Mobile Devices

4G LTE/5G: RF FE Sub-6GHz
RF SOI
Higher Data Rate
Power Efficiency

5G: RF FE mmWave
FDX™
Expanded Range
Power Efficiency

4G LTE/5G: Transceiver
FinFET
Higher Data Rate
Power Efficiency

Wi-Fi: Wi-Fi 6/6E
FinFET
Higher Data Rate
Power Efficiency

Camera: Optical Imaging
Feature-Rich CMOS
Sensor Fusion
Power Efficiency

Smart Audio
Feature-Rich CMOS (BCD, eNVM)
Audio Quality
Haptic Response

Secure Payment: NFC
Feature-Rich CMOS (eNVM)
Integration of NFC+ Secure Element
Secure Manufacturing

Touch Screen: Display
Feature-Rich CMOS
Functional Integration
Power Efficiency

Power Management: RF, Audio
Feature-Rich CMOS (BCDLite®), FDX™
Increased Efficiency
Smaller Form Factor

GF has 75% of silicon area in top premier smartphones in RF FE, Audio & NFC

Home and Industrial IoT

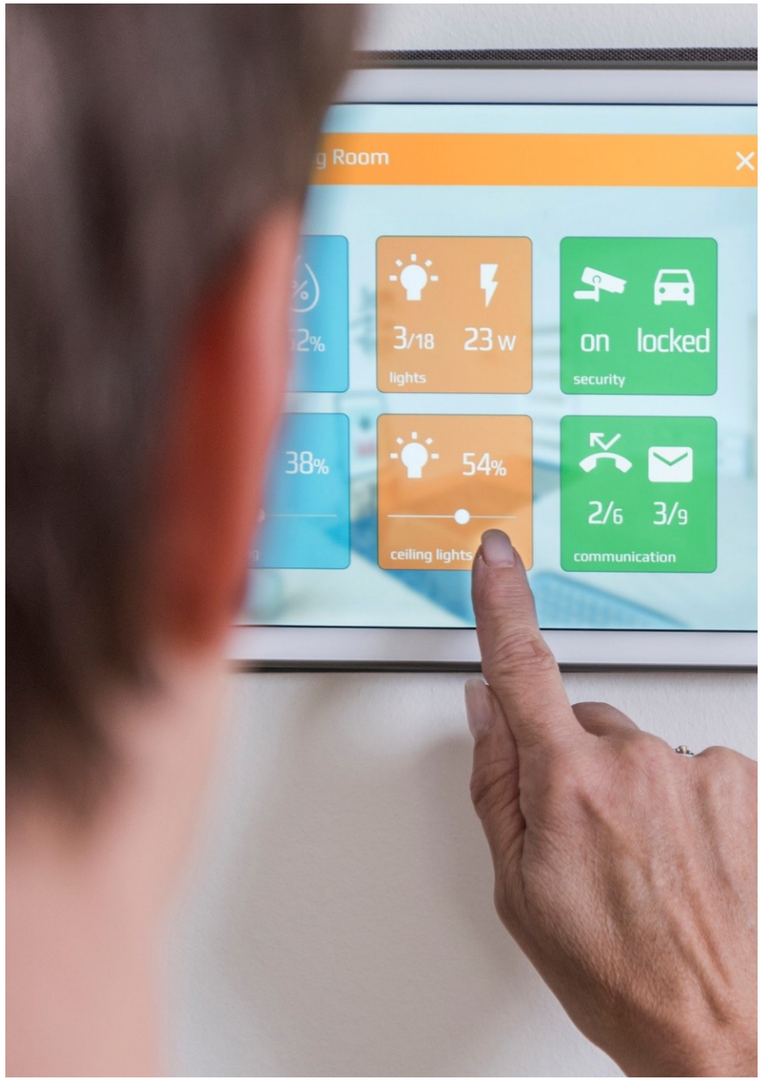
Smart Camera: Image Sensing
FDX™
Edge Intelligence
Low Power Connectivity

Smart Features: SoC
Feature-Rich CMOS
High Transfer Rate
Power Efficiency
Edge Intelligence

Smart Control: WL MCU
FDX™
Power
Wireless (BLE, Wi-Fi, 15.4)

Smart Features: MCU
Feature-Rich CMOS (BCD)
Power Management

Secure Transactions/ Interactions: NFC
Feature-Rich CMOS (eNVM)
Power Efficiency



Smart Speaker: Audio
Feature-Rich CMOS (BCD, eNVM)
Power Efficiency
Power Management

Wi-Fi Connection: Wi-Fi
FDX™
Edge Intelligence
Low Power Connectivity

Touch Screen: Display
Feature-Rich CMOS
Sensor Fusion
Power Efficiency

Medical IoT: Medical Sensing
FDX™
Edge Intelligence
Low Power Connectivity

Automotive

5G Connection:
RF FEM mmWave
FDX™
RF mmWave
Low Power Connectivity

Vehicle Power:
DC-DC, BMS, Charger
Feature-Rich CMOS (BCD, eNVM)
High Voltage
Precision
Power Efficiency
Power Management

Vehicle Network:
Zone/Domain/Fusion
Controllers
FDX™, FinFET
Power Efficiency
High Performance
High Temperature

Comfort/Customization/
Keyless Entry: MCU,
NFC, BLE, UWB
Feature-Rich CMOS (eNVM)
Power Efficiency
Edge Intelligence

ADAS: Radar
FDX™
RF mmWave
Power Efficiency
Edge Intelligence

Touch Screen: Display
Feature-Rich CMOS
Sensor Fusion
Power Efficiency

ADAS: LiDAR
Silicon Photonics
High Transfer Rate
Power Efficiency
Edge Intelligence

User Experience:
IVI, Cluster
Feature-Rich CMOS (BCD)
Power Efficiency
Power Management

Communications Infrastructure & Datacenter

5G Infrastructure: RF FEM mmWave
RF SOI, SiGe, 22FDX®
RF mmWave
Power efficiency

5G Infrastructure: Network processor / Switch
FinFET, Feature-Rich CMOS
Performance analog/mixed signal

Data communications: Redriver
SiGe
Signal loss compensation
Data reliability & integrity

4G LTE/5G Infrastructure: RF FEM Sub-6GHz
RF SOI, SiGe
RF features
Power efficiency

Connectivity: Optical networking
Silicon Photonics
Data throughput >4x Cu
Cu replacement for inter and intra DC connectivity

Chiplets/2.5D/3D: IOD
FinFET
Performance analog/mixed signal

Novel compute: AI/Photonics/Quantum
FinFET, Silicon Photonics
System integration: electronics & photonics
Highest performance/power efficiency

Power delivery
Feature-rich CMOS (BCDLite®)
High Voltage
High efficiency


GF is everywhere

Global Footprint

Manufacturing at a glance

99%

line yield up
to 15 years reliability

>31M

hours worked in 2020 at better
than safety benchmarks

5

manufacturing sites
across three continents

800 NPIs

per year, ramped in 6-
9 months to HVM

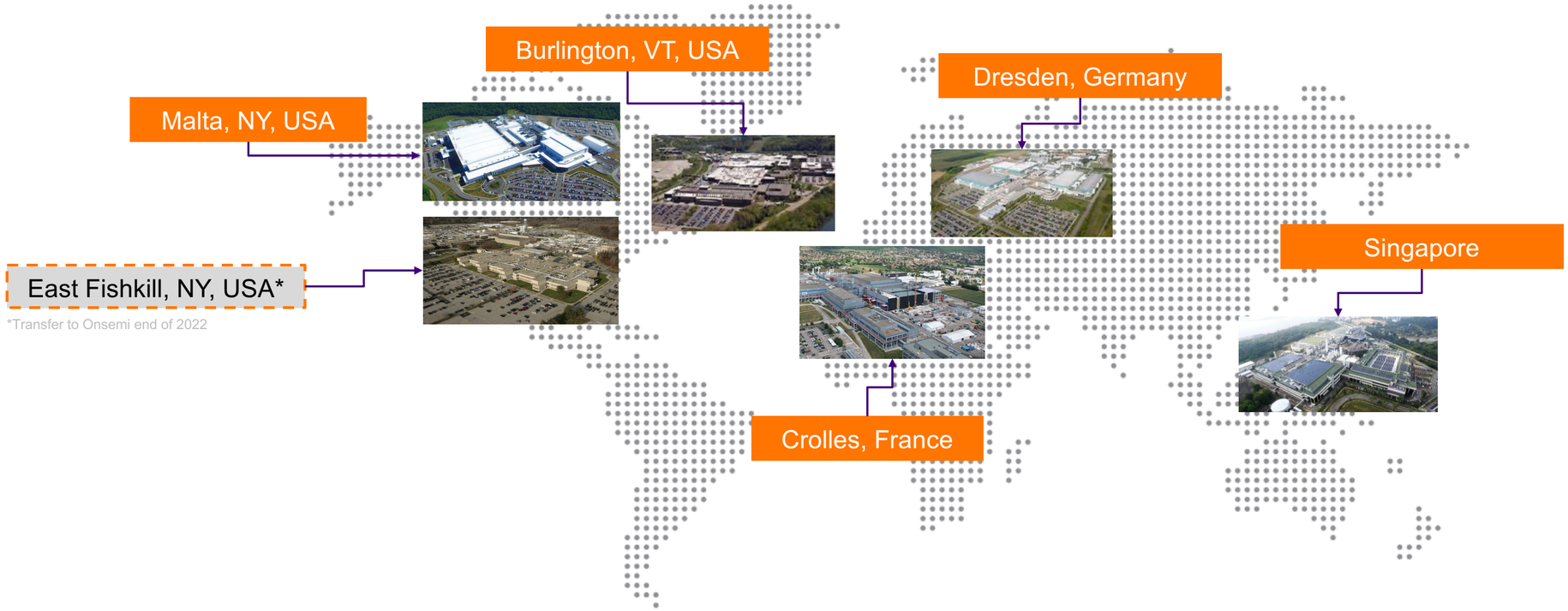
99%

on time delivery

Zero

stock outs impacting customer
commitments

Global manufacturing footprint & strategy



*Transfer to Onsemi end of 2022

Supply chain security through dual-technology qualification

Economies of scale through modular expansion at existing sites

+50%
Capacity increase by 2020 vs 2025

Capital efficiency through partnership model

Global manufacturing footprint - current

Asset Sale Transfer End of 2022

Malta, NY, USA
300mm

Capacity: 400 kwpa
Technology: FinFET, NVM, RFSOI, SiPh

Singapore
300mm & 200mm

Capacity: 730 & 370 kwpa
Technology: BCD/BCDLite, HV, NVM, DDI, RFSOI, LP SiGe

Dresden, Germany
300mm

Capacity: 680 kwpa
Technology: FDX™, NVM, HV, BCDLite

Burlington, VT, USA
200mm

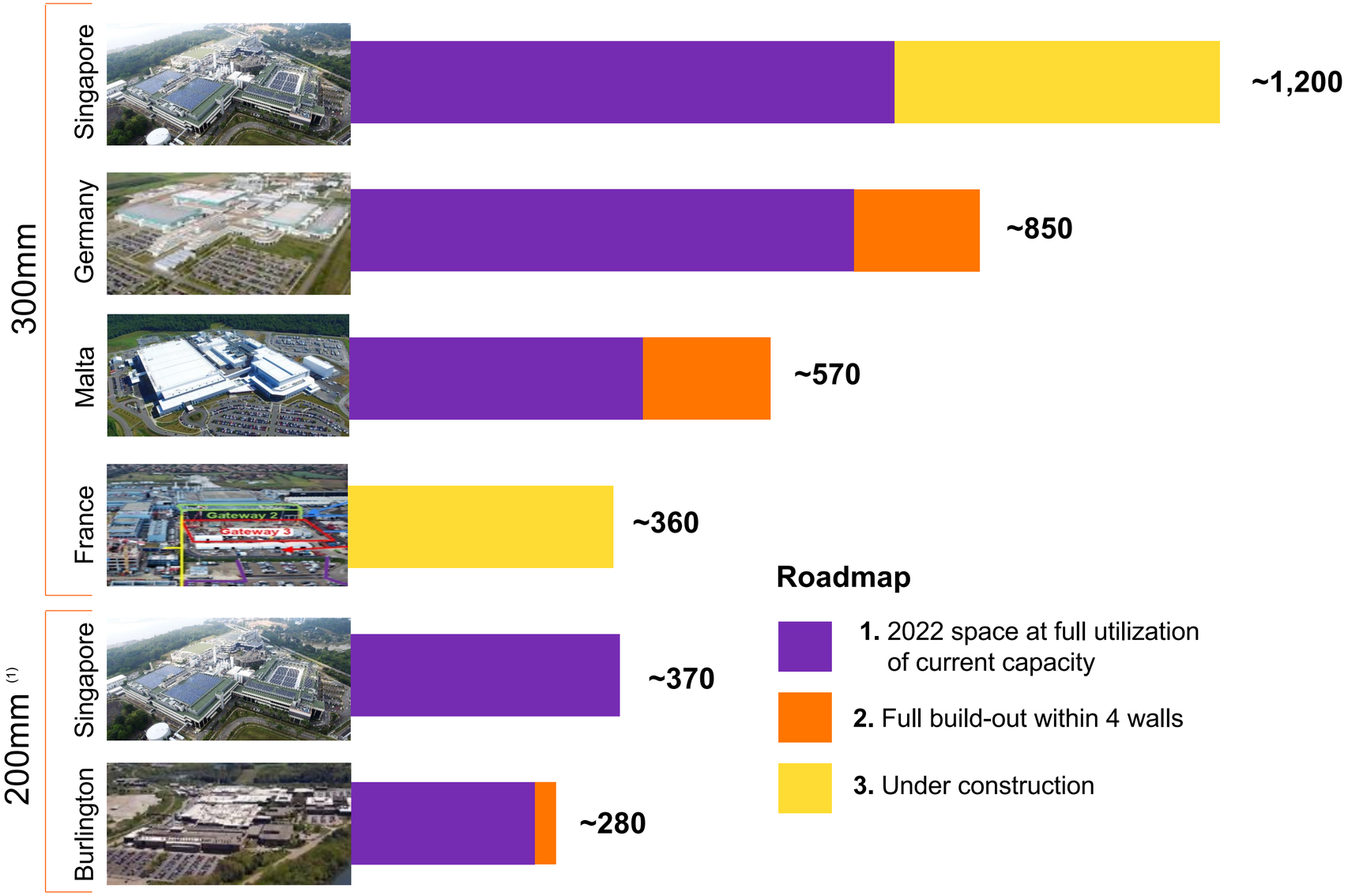
Capacity: 250 kwpa
Technology: RFSOI, SiGe, GaN

East Fishkill, NY, USA
300mm

Capacity: 150 kwpa
Technology: HP CMOS, RFSOI

Note:
1. Kwpa is defined as 2022 capacity in thousand wafers per annum
2. 200mm capacity translated to 300mm equivalent

Capacity expansion roadmap



Global manufacturing FOOTPRINT focused on supply security, diversity & sustainability

>50% capacity expansion from 2020 levels

Economy of scale through modular expansion at existing sites in global footprint

Dual site sourcing provides flexibility & security

25% GHG reduction in emissions by 2030

Notes:

1. 200mm capacity translated to 300mm equivalent, in kwpa. 2. Full build up Plan through 2028. 3. Does not include future capacity plans under development

Global manufacturing footprint – beyond ‘23

Malta, NY, USA *300mm*	**Capacity:** 570 kwpa **Technology:** FinFET, NVM, RFSOI, SiPh
Singapore *300mm & 200mm*	**Capacity:** 1,200 kwpa & 370 kwpa **Technology:** BCD/BCDLite, HV, NVM, DDI, RFSOI, LP SiGe
Dresden, Germany *300mm*	**Capacity:** 850 kwpa **Technology:** FDX™, NVM, HV, BCDLite
Burlington, VT, USA *200mm*	**Capacity:** 280 kwpa **Technology:** RFSOI, SiGe, GaN
Crolles, France *300mm*	**Capacity:** 360 kwpa **Technology:** 22FDX®

Note:
1. Kwpa is defined as 2022 capacity in thousand wafers per annum
2. 200mm capacity translated to 300mm equivalent

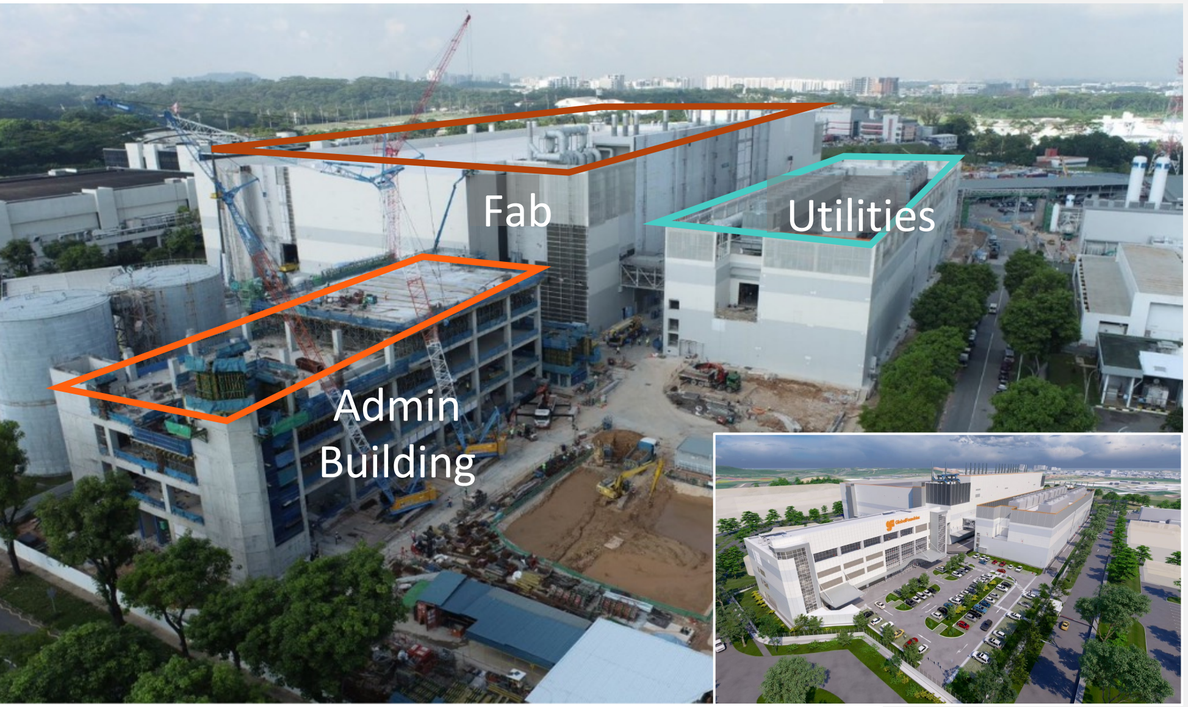
Crolles, France partnership with STMicroelectronics

Phase 0: Install 20 unique FDX™ tools to form pilot line for technology transfer starting 2023

Phase 1-3: Ramp starts Q4'24. Full build up to 360kwpa

GF co-managed facility

- On site GF management supplemented by Dresden expertise
- Direct oversight of all planning and operations
- Depreciation, fixed and variable cost sharing model based on actual utilization and consumption
- Stable and low-cost energy supply through French Nuclear energy network



Singapore modular expansion

First tool-in announced in June 2022

Ready for production in 2023

>1.5M of 300mm equivalent wafers serving Auto, Mobile and IoT

Secured government grants and customer commitments

Malta, NY expansion

Expansion announced in July 2021

Planning and preliminary permitting underway

Strong government and customer partnerships

CHIPS and Science Act signed into law in August 2022

Sustainable operations

100%

of 3TG minerals we use are conflict free

Journey to **ZERO** Carbon

	2015-2021	2022 and Beyond
	**38%** Reduction in electricity use intensity	**33%** Reduction in electricity use intensity by 2025
	**36%** Reduction in GHG emissions intensity	**25%** Absolute reduction in GHG emissions by 2030 (1)
	**40%** Reduction in water use intensity	**33%** Reduction in water use intensity by 2025
	**62,100** Tons annualized reduction of chemical use and waste	**90%** Landfill avoidance in 2022

Note:
1. GHG emissions include scope 1 and 2

Technology Development

Technology Development at a glance

~1400

technologists in dedicated research teams

>30K

wafers per year dedicated to development

>50

universities, government partners and other research institutes partnered in collaborative efforts

>150

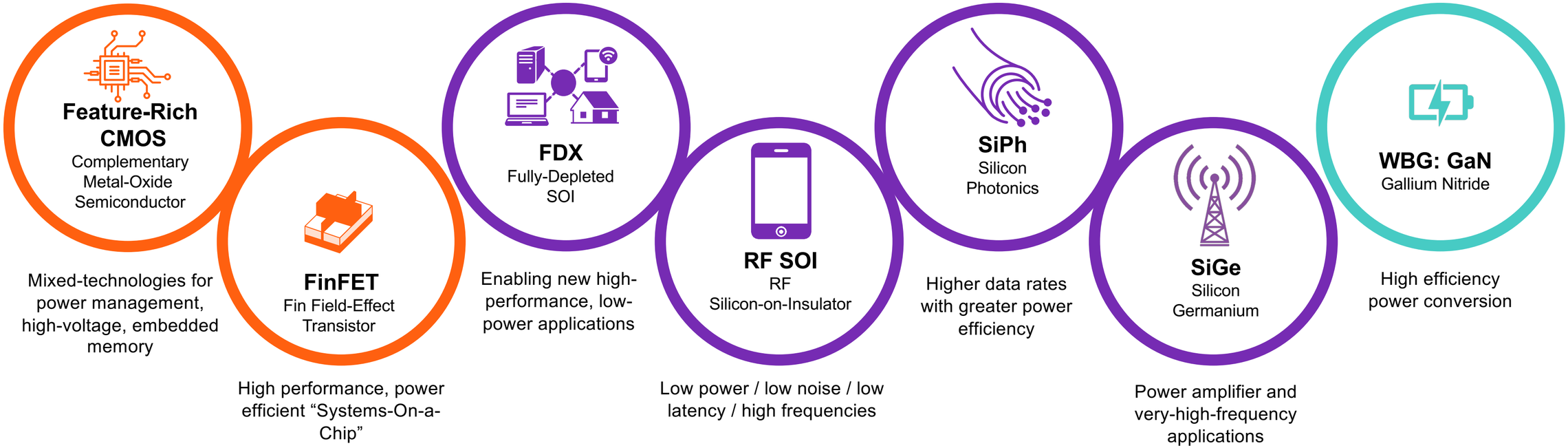
differentiated programs built on 25+ world class platforms

Innovation through market-driven purpose-built platforms

Optimizing digital processing & application specific features

The ultimate in low power, performance with superior connectivity

Innovating beyond silicon



Innovation beyond transistor size

How we innovate: Smart Mobile Device

Ultra-fast, seamless, reliable connectivity

End user applications

Bridging the cellular and wireless experience effortlessly

Capabilities required

- **Rate**
- **Range**
- **Power**

GF's differentiated performance

RF SOI

FDX™

SiGe

GaN

Investing for a bold future

Feature-Rich CMOS

130nm
BCDLite®Gen1
BCDLite®Gen2
BCD
Auto
BCD+NVM
BCD 120V
55nm
BCDLite®
eNVM
BCD
IVR
SPAD/BSI
Auto
40nm
Auto
ISP
DDI/HV
eNVM
mmW
28nm
ISP
DDI/HV
eNVM
BCDLite®
µLED

FinFET

12LP
Auto
RF
IC
12LP+
ULP
HDLV
RRAM
ATV-150

FDX™ FD-SOI

22FDX
ULL / ULP
RF/ mmW
MRAM
Auto
ISP
RRAM
IVR
TSV
HBT
22FDX+
ULL/ULP
RF-Gen2
MRAM-G2
RRAM
12FDX
RF/mmW
ULL/ULP

RF SOI

180nm
7SW
LNA
SW
PA
NSX
NSX-Gen2
8SW
LNA
SW
Low latency
LNA
EDMOS
PA
9SW
90nm
45RFSOI
45nm

SiPh

90nm
90WG
250um pitch
Fiber Array
attach
High Power
Wave Guides
45CL0
127um pitch
Fiber Attach
TSV
On-Die Laser
Micro-ring
Modulators
Custom
45SP3
45SPQ

SiGe

130nm
Power Amp
8HP+
Power Amp
TSV
9HP
Power Amp
9HP+
45SG01
Power Amp
40LP-SiGe

GaN/Si (WBG)

GaN/Si
PA
Power

Huge features portfolio:
120 technology solutions enabling thousands of customer products

2022 expansion:
+16 technology solutions
+ 6 new platforms
+ dozens of new features in dev.

Beyond Si solutions:
Adding wide bandgap materials for power and RF – GaN/Si

Production Platform Features | Development Platform Features

Physical sciences innovation

- Materials enabling new capabilities
- New devices to extend and expand applications
- Advanced tooling and processes

Design innovation

- System level architecture explorations
- Heterogeneous integration
- AI-enabled design
- Circuit topologies

gf LABS

Partnership / ecosystem

- Expanded university engagements
- Customer collaborative projects
- Government supported and targeted R&D
- Lab-to-lab

Market Focus

- 6G and beyond
- AR / VR
- Datacenter
- Quantum computing
- Automotive

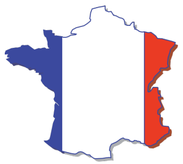
GF Labs: Our R&D ecosystem of partners

University Partnerships

Princeton University
UC Riverside Marlan and Rosemary Bourns College of Engineering
UC San Diego
KU Leuven
The Ohio State University
Rice
Georgia Institute of Technology
UCI Samueli School of Engineering, University of California, Irvine
Rensselaer
Nanyang Technological University
Purdue University
University of Massachusetts Amherst
UC Santa Barbara
Texas Tech University
Lund University
The University of Texas at Dallas
NUS National University of Singapore
Technische Universität Berlin
University of Calgary
Technische Universität Dresden
University of Twente, The Netherlands

Government Partnerships

Department of Defense, United States of America
European Commission
EDB Singapore
DARPA



Consortia / R&D Institutes

CMC Microsystems
imec
SRC Semiconductor Research Corporation
leti cea tech
MITRE ENGENUITY
Fraunhofer
A*STAR IME
PowerAmerica
Advancing Silicon Carbide and Gallium Nitride technologies.
ASIC American Semiconductor Innovation Coalition

Environmental, Social Governance

Commitment to ESG

Environmental

Journey to Zero Carbon: 25% Greenhouse Gas (GHG) emissions reduction by 2030

>36K annualized metric tons of Carbon equivalent savings achieved in 2019 / 2020

>415K annualized cubic meters water savings achieved in 2019 / 2020

Social

13 total GF Awards in 2019, 2020 and 2021 for exceptional performance in CSR and EHS

200 / 200: Perfect scores in 2020-2021 Responsible Business Alliance audits

World Class: GF TRIR 2020 safety rate (0.13) lowest in our history

GF named one of "**America's Safest Companies**" in 2020*

Governance

4 independent Board directors

Independent audit, risk, and compliance committee

Experienced global compliance function

Enterprise **risk management framework**

Conflict-free supply chain for 3TG: gold, tantalum, tungsten and tin

Source: EHS Today*

GFShield: a foundation of trust

Beneficial geopolitical landscape

During times of increasing international trade conflicts, GF benefits from the resilience of global scale of operations in stable low-risk geographies (United States, Germany and Singapore)

Pedigree of secure at-scale manufacturing

1. Only pure-play foundry in The United States Department of Defense Trusted Foundry Program
2. ISO 15408 Certification to manufacture Common Criteria Secure Products
3. ISO 27001 Certification for Information Security Management

Intellectual Property (IP) protection

With an industry-leading track record protecting GF IP and customers' IP

In a world of escalating threats and risks in the technology sector, our foundation of trust offers a strong competitive edge

Supply chain responsibility, resiliency and security

100%

of 3TG minerals we use are conflict free

Responsible Business Alliance

Advancing Sustainability Globally

" Completed the RBA validated audit process achieving PLATINUM status with a full audit score of 200/200 "

RBA Recognition, Fab 9

GlobalFoundries™

INFORMATION OPERATIONAL GFSHIELD SECURITY PRODUCT CYBER

Trusted Supplier to DoD

Critical Supplier - Defense Production Act

Stable and Diverse Geographic Footprint

Our Team and Culture

Our global team

~15,000
employees

>90
nationalities in
13 countries

>1000
new college graduates hired
2018 – present

~25%
female workforce

~10,500
employees working in
STEM fields

~75%
employees with university
degrees (PhD, masters,
bachelors)

~80%
engineers, technicians
and operators

GF senior leadership team

Dr. Thomas Caulfield
CEO & President

David Reeder
Chief Financial Officer

Juan Cordovez
Chief Commercial Officer

Mike Hogan
Chief Business Officer

Gregg Bartlett
Chief Technology Officer

KC Ang
Chief Manufacturing Officer

Mike Cadigan
Chief Quality Officer

Kevin Soukup
Chief Strategy Officer

Pradheepa Raman
Chief People Officer

Laurie Kelly
Chief Communications Officer

Saam Azar
General Counsel

GF board of directors

Ahmed Yahia
Chairman of the Board

Dr. Thomas Caulfield

Tim Breen

Ahmed Saeed Al Calily

Glenda Dorchak
Independent

Martin L. Edelman

David Kerko
Independent

Jack Lazar
Independent

Elissa Murphy
Independent

Carlos Obeid

Bobby Yerramilli-Rao
Independent

Investing in our team and communities

1.4M
hours invested in training our employees in 2020

>4300
GlobalGives employee members

$1.2M
donated in 2021, includes employee donations with corporate funding

>2500
Employee resource group members worldwide

- GlobalWomen
- BRAG (Black Resource Affinity Group)
- GlobalFamilies
- VRG (Veterans Resource Group)
- Early Career and Tenure Resource Group
- Unidos, Hispanic/Latinx Resource Group
- ASIA (Asian Society for Inclusion and Awareness), AAPI Resource Group
- Pride@GF, LGBTQ+ Resource Group

Our Mission

We innovate and partner with our customers to deliver technology solutions for humanity.

We manufacture semiconductors around the globe.

Our Vision

We are changing the industry that is changing the world.

Our Values

Create

- Innovate beyond what is possible today
- Differentiate our technology to enable customer success
- Have a passion for problem-solving
- Create value for our customers and for our shareholders

Partner

- Collaborate across all borders & boundaries
- Strive for win-win outcomes
- Build trust as the basis of every relationship

Embrace

- Diversity is a competitive advantage
- The best ideas comes from being inclusive
- Act with a shared sense of purpose
- Respect everyone

Deliver

- Our customers can count on us to deliver on our commitment
- Work effectively, efficiently and decisively
- Focus on outcomes and are accountable for results
- Celebrate and reward success
- Nothing matters without safety

All with unyielding integrity

Links

GF.com

News & Events

GF Investor Relations Website

GF Leadership Team

GF Board of Directors

Diversity & Inclusion

Environmental Social Governance at GF

Careers at GF

Connect with GF

GlobalFoundries

@GlobalFoundries

GlobalFoundries

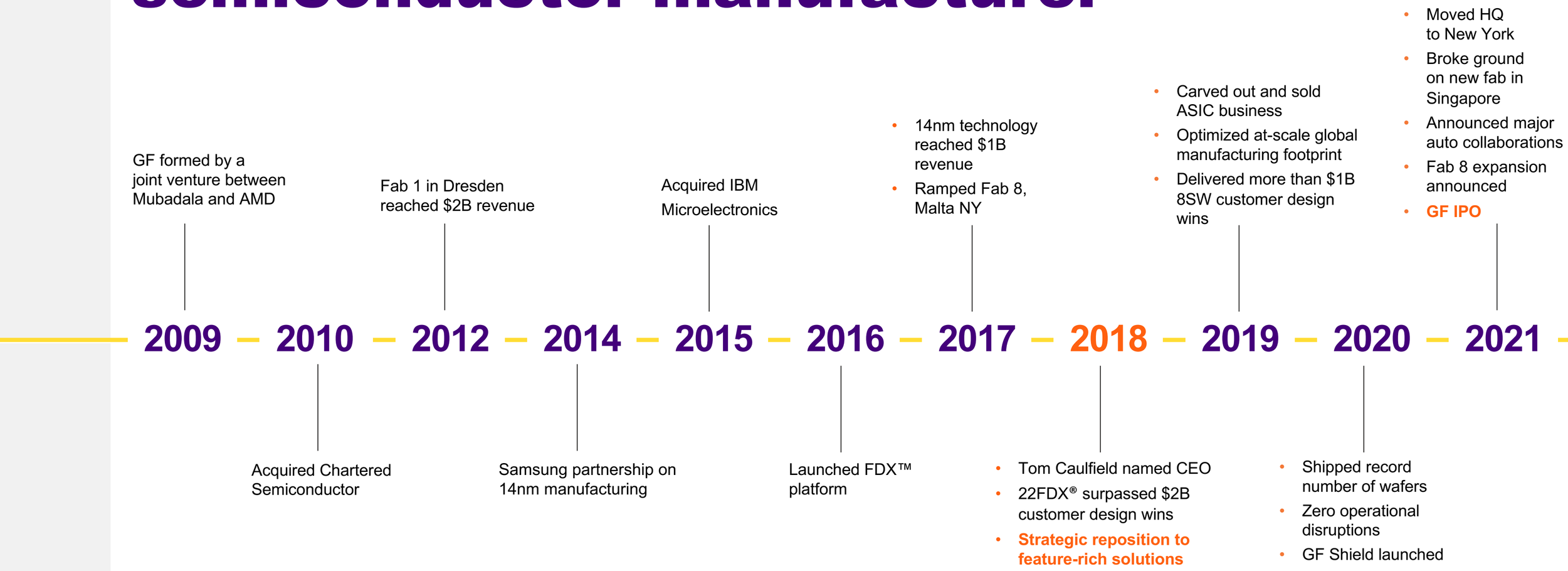
GlobalFoundries.Corporate

Thank You

Q4 2022-1

Appendix

The making of a global semiconductor manufacturer



How we innovate: Industrial & Home IoT

End user applications

Smart home appliances

Smart speaker

Security system

Capabilities required

Intuitive

Pain-free

Efficient

Convenient

Trusted

GF's differentiated performance

FDX®

Feature rich CMOS

BCD

NVM

How we innovate: next gen 5G infrastructure

End user applications

Increased range + greater area coverage

Increased data rate + low latency for HD video and AR/VR

Capabilities required

5G sub 8GHz / mmWave

Satellite Communications

Reliability / availability

GF's differentiated performance

SiGe

Feature-rich CMOS

FDX ®

How we innovate: Smart Mobile Device

End user applications

Hyperconnected human experience bridging physical & digital worlds

Capabilities required

- Touch
- Hear
- See
- Trust

GF's differentiated performance

- FDX®
- BCDL®
- NVM
- HV

How we innovate: Industrial & Home IoT

End user applications

Video streaming

Connected camera

Smart home

Capabilities required

Rate

Range

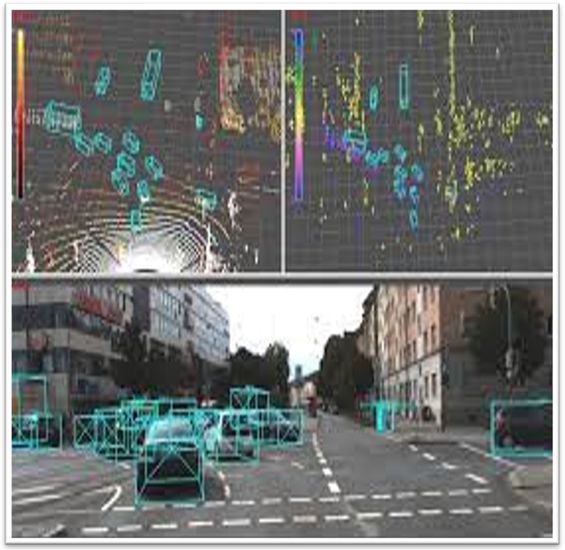
Battery life

GF's differentiated performance

FDX®

How we innovate: ADAS

End user applications



Autopilot in highway and urban traffic scenarios

Capabilities required

- Range
- Field of view
- Resolution
- Robustness
- Power
- Intelligence

GF's differentiated performance

FDX ®

SiGe

Feature-rich CMOS

FinFET

How we innovate: Automotive

End user applications

300+ mile range

Delivering a smartphone like user experience

Time to charge

Capabilities required

Efficient power:

- Creation
- Conversion
- Monitoring

GF's differentiated performance

BCD

Feature-rich CMOS

GaN

Manufacturing operations leadership

KC Ang
Chief Manufacturing Officer

Peter Benyon
SVP and GM Malta, NY Fab

Joseph Chia
VP and GM GIGA+ Singapore Fab

Zhimin Gu
VP, New Singapore Fab Operations

Manfred Horstmann
SVP and GM European Fabs

Ken McAvey
VP and GM Burlington, VT Fab

Neil Peruffo
VP and GM East Fishkill, NY Fab

Pradip Singh
SVP & GM, Global Manufacturing Operations Excellence

Yew Kong Tan
SVP and GM Singapore Fabs